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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				ATTY. DOCKET NO. MI22-2266	SERIAL NO. Filed herewith		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Micron Technology, Inc.			
				FILING DATE Filed herewith	GROUP		
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>J.H.</i>	AA	6,187,679	2/13/01	Cabral, Jr. Et al.			
<i>J.H.</i>	AB	6,362,086	3/26/02	Weimer et al.			
<i>J.H.</i>	AC	5,852,319	12/22/98	Kim et al.			
<i>J.H.</i>	AD	5,997,634	12/7/99	Sandhu et al.			
<i>J.H.</i>	AE	6,090,708	7/18/00	Sandhu et al.			
<i>J.H.</i>	AF	6,306,766	10/23/01	Sandhu et al.			
	AG						
	AM						
	AI						
	AJ						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes
							No
	AK						
	AL						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
<i>J.H.</i>	AM		'Mechanisms for enhanced C54-TiSi _x formation in Ti-Ta alloy films on single-crystal Si'; A. Quintero et al.; Journal of Materials Research; Vol. 14, No. 12 Dec. 1999 pp. 4690-4700				
<i>J.H.</i>	AN		'Enhanced formation of the C54 TiSi _x by an interposed layer of molybdenum'; A. Mouroux et al.; Appl. Phys. Lett. 69 (7), 12 August 1996; ©1996 American Institute of Physics				
<i>J.H.</i>	AO		'Low temperature formation of C54-TiSi _x using titanium alloys'; C. Cabral, Jr. Et al; Appl./ Phys. Lett. 71 (24) 15 December 1997 ©1997 American Institute of Physics; pp. 3531-3533				
	AP						
EXAMINER	<i>Jayne A. Husley</i>			DATE CONSIDERED		9/18/04	
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